

L Number	Hits	Search Text	DB	Time stamp
50	143	(individual\$3 with (shutter shield) with (coat\$3 deposit\$3))	USPAT; US-PGPUB	2003/06/27 13:23
51	60	((individual\$3 with (shutter shield)) same (coat\$3 deposit\$3))	EPO; JPO; DERWENT	2003/06/27 13:23
52	457	((118/720) or (118/721)).CCLS.	USPAT; US-PGPUB	2003/06/27 13:51
53	5	((((118/720) or (118/721)).CCLS.) and ((individual each) with (shutter shield))	USPAT; US-PGPUB	2003/06/27 13:53
54	53	(156/345.3).CCLS.	USPAT; US-PGPUB	2003/06/27 13:54
55	69	(118/\$.CCLS.) and ((shield shutter) with (individual))	USPAT; US-PGPUB	2003/06/27 14:13
56	607	(118/504).CCLS.	USPAT; US-PGPUB	2003/06/27 14:13
-	453	((118/720) or (118/721)).CCLS.	USPAT; US-PGPUB	2003/06/27 13:51
-	0	((((118/720) or (118/721)).CCLS.) and (laser with shutter with individual)	USPAT; US-PGPUB	2003/03/21 09:41
-	2	((((118/720) or (118/721)).CCLS.) and (laser with shutter)	USPAT; US-PGPUB	2003/03/21 09:32
-	1	("5980975").PN.	USPAT; US-PGPUB	2003/03/21 09:32
-	11	((((118/720) or (118/721)).CCLS.) and (shutter with (individual multipl\$5 plural\$5))	USPAT; US-PGPUB	2003/03/21 12:40
-	104	(118/\$.CCLS.) and (shutter with (individual multipl\$5 plural\$5))	USPAT; US-PGPUB	2003/06/27 14:04
-	27	("2432950" "2571167" "2765765" "2906235" "2978364" "3063867" "3117025" "3352282" "3371138" "3502051" "3504325" "3549414" "3573672" "3600675" "3670693" "3756851" "3773541" "3866155" "3963982" "3992760" "4093914" "4107349" "4122147" "4323031" "4343827" "4378382" "4391034").PN.	USPAT	2003/03/21 12:48
-	8	("3853740" "4051010" "4410407" "4894132" "5076205" "5241152" "5490912" "5665214").PN.	USPAT	2003/03/21 13:04
-	460	shutter with (individual multipl\$5 plural\$5) with (substrate wafer semiconductor laser)	USPAT; US-PGPUB	2003/03/21 13:22
-	413	(shutter with (individual multipl\$5 plural\$5) with (substrate wafer semiconductor laser)) not ((118/\$.CCLS.) and (shutter with (individual multipl\$5 plural\$5)))	USPAT; US-PGPUB	2003/03/21 13:19
-	277	(shutter with (individual multipl\$5 plural\$5) with (substrate wafer semiconductor)) and (deposit\$3 coat\$3 (form\$3 with film))	USPAT; US-PGPUB	2003/03/21 13:25
-	277	(shutter with (individual multipl\$5 plural\$5 each) with (substrate wafer semiconductor)) and (deposit\$3 coat\$3 (form\$3 with film))	USPAT; US-PGPUB	2003/06/27 12:56
-	91	(shutter with (individual multipl\$5 plural\$5 each) with (substrate wafer semiconductor)) and (deposit\$3 coat\$3 (form\$3 with film))	EPO; JPO; DERWENT	2003/03/21 13:28